EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	4218626	(microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$ or chip$1 or semiconductor$1)and (initial or second)state	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 14:55
L2	3065655	L1 and (@ad<"20020718" or @rlad<"20020718" or @prad<"20020718" or @ptad<"20020718")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 14:59
L3	45	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$ or chip$1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:05
L4	47	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$ or chip$1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain) and(multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:06
L5	47	L4 and (@ad<"20020718" or @rlad<"20020718" or @prad<"20020718" or @ptad<"20020718")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:06
L6	28	L4 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:06

L7	0	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$ or chip$1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal)and(multiple adj layers or area or regions)and (sub adj image$1 or subimage $1)and correlation and(array or matrics)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:10
L8	0	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$ 1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal)and(multiple adj layers or area or regions)and (sub adj image$1 or subimage $1)and correlation and(array or matrics)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:10
L9	16	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal)and(multiple adj layers or area or regions)and correlation and(array or matrics)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:11
L10	16	L9 and (@ad<"20020718" or @rlad<"20020718" or @prad<"20020718" or @ptad<"20020718")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:11
L11	8	L10 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:11

L12	60	L2 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal)and(multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:14
L13	32	L12 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:14
L14	10	((CHUNG) near2 (SEE)).INV.	US-PGPUB; USPAT	OR	ON	2008/09/19 15:22
L15	4	((MICHAEL) near2 (SOMEKH)).INV.	US-PGPUB; USPAT	OR	ON	2008/09/19 15:22
L16	1	((MARK) near2 (PITTER)).INV.	US-PGPUB; USPAT	OR	ON	2008/09/19 15:23
L17	1	L14 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:24
L18	1	L15 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:25

L19	1	L16 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:25
L20	90	(("(4839692") or ("4923848") or ("5451560") or ("5629259") or ("5707925") or ("5940111") or ("4911543") or ("5001576") or ("5235437") or ("5236780") or ("5408300") or ("5420979") or ("5445910") or ("5513274") or ("5672223") or ("5767860") or ("6064847") or ("6202073") or ("4353975") or ("4359517") or ("4515461") or ("5177796") or ("5259043") or ("5267030") or ("5298308") or ("5327263") or ("5379127") or ("5394875") or ("5452111") or ("5510230") or ("5571656") or ("5649267") or ("5701361") or ("5717779") or ("5736286") or ("5790183") or ("5825945") or ("5851717") or ("5880778") or ("5886818") or ("5956044") or ("5965485") or ("6101291") or ("4273863") or ("4276829") or ("4492177") or ("4518674") or ("4568625") or ("4576889") or ("4797942") or (").pn.")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/19 15:26
L21	90	L20 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:26
L22	0	L21 and analysis and (microelectronic or ultra adj sound or transducer)and measur$3 adj deformat$3 and (substrate or wafer$1 or chip $1 or semiconductor$1 or package adj device)and(detect $3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:26

L23	0	L21 and analysis and measur$4 adj deformat$3 and (substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)and (detect$3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:28
L24	0	L21 and measur$4 adj deformat$3 and(substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)and(detect$3 or determining)and(stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and(multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:28
L25	0	L21 and deformat$3 and (substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)and (detect$3 or determining)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:28
L26	0	L21 and deformat$3 and (substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)and (stresses or delamination or hotspots or cracking or strain or thermal adj image$1)and (multiple adj layers or area or regions)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:28
L27	1	L21 and deformat$3 and (substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:29

L28	1	L27 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:29
L29	137693	deformat$3 and(substrate or wafer$1 or chip$1 or semiconductor$1 or package adj device or microelectronic or ultra adj sound or transducer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:30
L30	3	"6516084".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:38
L31	2	L30 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:38
L32	6	(("(5386117") or ("5637871") or ("6447460") or ("6606115").pn.")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/09/19 15:49
L33	6	L32 and @ad<"20020718"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/09/19 15:49

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